

2. AMENDMENTS TO THE ABSTRACT.

Replace the abstract of the disclosure with the following:

ABSTRACT OF THE DISCLOSURE

A cooler for cooling of electronic components ~~comprising~~ comprises at least two heatsinks thermally connected with each other by heat spreading means, and ~~at least one a~~ a double inlet centrifugal blower ~~comprising~~ comprises a casing with two inlets and an outlet, ~~[[an]]~~ a radial impeller with an axle and an electric drive. ~~[[Said]]~~ The cooler thermally connected with ~~[[said]]~~ the electronic component. Each of ~~[[said]]~~ the heatsinks comprises inflow and outflow openings, and thermally connected heat exchanging means and a base. The impeller comprises radial blades located from both sides of an impeller disk. ~~[[Said]]~~ The double inlet centrifugal blower is located between ~~[[said]]~~ the heatsinks thus each of ~~[[said]]~~ the outflow openings is coincided with ~~[[said]]~~ the closest inlet, so cooling air flows through ~~[[said]]~~ the inflow openings, ~~[[said]]~~ the heat exchanging means, ~~[[said]]~~ the outflow openings and ~~[[said]]~~ the inlets of ~~[[said]]~~ the blower in a series way. ~~Said base of at least one of said heatsinks is thermally connected with said electronic component. Said heat spreading means are made as at least one heat pipe comprising evaporator and condenser parts that thermally connected with said bases of two different heatsinks, or as a high heat conductive plate located from one side of and perpendicularly to said bases.~~